

CM400HA-24A

HIGH POWER SWITCHING USE

ELECTRICAL CHARACTERISTICS ($T_j = 25\text{ }^\circ\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Units
I_{CES}	Collector cutoff current	$V_{CE}=V_{CES}, V_{GE}=0V$	—	—	1	mA
$V_{GE(th)}$	Gate-emitter threshold voltage	$I_C=40mA, V_{CE}=10V$	6	7	8	V
I_{GES}	Gate leakage current	$V_{GE}=V_{GES}, V_{CE}=0V$	—	—	0.5	μA
$V_{CE(sat)}$	Collector to emitter saturation voltage	$T_j=25\text{ }^\circ\text{C}$ $I_C=400A$	—	2.1	3.0	V
		$T_j=125\text{ }^\circ\text{C}$ $V_{GE}=15V$	—	2.4	—	
C_{ies}	Input capacitance	$V_{CE}=10V$	—	—	70	nF
C_{oes}	Output capacitance	$V_{GE}=0V$	—	—	6	
C_{res}	Reverse transfer capacitance		—	—	1.4	
Q_G	Total gate charge	$V_{CC}=600V, I_C=400A, V_{GE}=15V$	—	2000	—	nC
$t_{d(on)}$	Turn-on delay time	$V_{CC}=600V, I_C=400A$	—	—	550	ns
t_r	Turn-on rise time	$V_{GE1}=V_{GE2}=15V$	—	—	180	
$t_{d(off)}$	Turn-off delay time	$R_G=0.78\Omega$, Inductive load	—	—	600	
t_f	Turn-off fall time	switching operation	—	—	350	
t_{rr} ①	Reverse recovery time	$I_E=400A$	—	—	250	ns
Q_{rr} ①	Reverse recovery charge		—	16	—	μC
V_{EC} ①	Emitter-collector voltage	$I_E=400A, V_{GE}=0V$	—	—	3.8	V
$R_{th(j-c)Q}$	Thermal resistance	IGBT part *1	—	—	0.046	$^\circ\text{C/W}$
$R_{th(j-c)R}$		FWDi part *1	—	—	0.085	
$R_{th(c-f)}$	Contact thermal resistance	Case to fin, Thermal compound Applied *2	—	0.02	—	
R_G	External gate resistance		0.78	—	10	Ω

*1: T_c, T_f measured point is just under the chips.

*2: Typical value is measured by using Shin-etsu Silicone "G-746".

- ① I_E, V_{EC}, t_{rr} & Q_{rr} represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).
- ② Pulse width and repetition rate should be such that the device junction temp. (T_j) dose not exceed T_{jmax} rating.
- ③ Junction temperature (T_j) should not increase beyond 150°C .
- ④ Pulse width and repetition rate should be such as to cause neglible temperature rise.